Lattice Semiconductor Corporation - LFE2-12SE-6Q208C Datasheet

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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	1500
Number of Logic Elements/Cells	12000
Total RAM Bits	226304
Number of I/O	131
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-12se-6q208c

LatticeECP2/M Family Data Sheet Architecture

September 2013 **Data Sheet DS1006**

Architecture Overview

Each LatticeECP2/M device contains an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM™ Embedded Block RAM (EBR) and rows of sysDSP™ Digital Signal Processing blocks, as shown in Figure 2-1. In addition, the LatticeECP2M family contains SERDES Quads in one or more of the corners. Figure 2-2 shows the block diagram of ECP2M20 with one quad.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and Programmable Functional Unit without RAM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM and ROM functions. The PFF block contains building blocks for logic, arithmetic and ROM functions. Both PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and efficiently. Logic Blocks are arranged in a two-dimensional array. Only one type of block is used per row.

The LatticeECP2/M devices contain one or more rows of sysMEM EBR blocks. sysMEM EBRs are large dedicated 18K fast memory blocks. Each sysMEM block can be configured in a variety of depths and widths of RAM or ROM. In addition, LatticeECP2/M devices contain up to two rows of DSP Blocks. Each DSP block has multipliers and adder/accumulators, which are the building blocks for complex signal processing capabilities.

The LatticeECP2M devices feature up to 16 embedded 3.125Gbps SERDES (Serializer / Deserializer) channels. Each SERDES channel contains independent 8b/10b encoding / decoding, polarity adjust and elastic buffer logic. Each group of four SERDES channels along with its Physical Coding Sub-layer (PCS) block, creates a quad. The functionality of the SERDES/PCS Quads can be controlled by memory cells set during device configuration or by registers that are addressable during device operation. The registers in every quad can be programmed by a soft IP interface, referred to as the SERDES Client Interface (SCI). These quads (up to four) are located at the corners of the devices.

Each PIC block encompasses two PIOs (PIO pairs) with their respective sysI/O buffers. The sysI/O buffers of the LatticeECP2/M devices are arranged in eight banks, allowing the implementation of a wide variety of I/O standards. In addition, a separate I/O bank is provided for the programming interfaces. PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs. The PIC logic also includes pre-engineered support to aid in the implementation of high speed source synchronous standards such as SPI4.2, along with memory interfaces including DDR2.

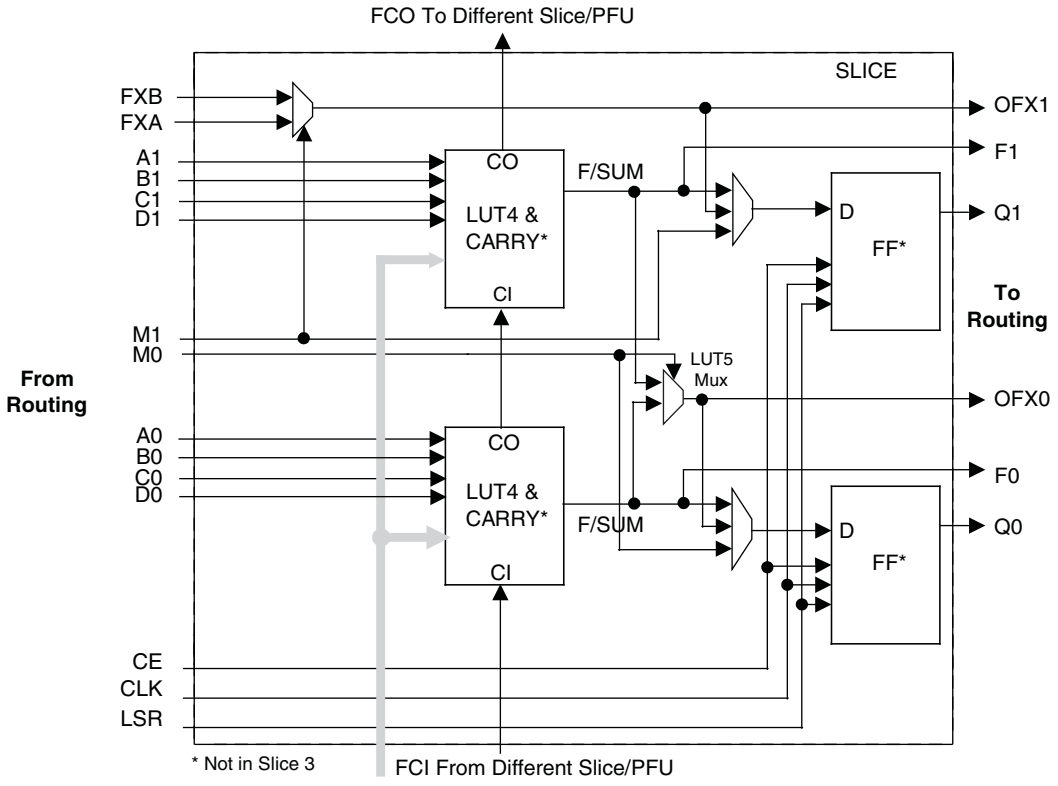
The LatticeECP2/M registers in PFU and sysI/O can be configured to be SET or RESET. After power up and the device is configured, it enters into user mode with these registers SET/RESET according to the configuration setting, allowing the device entering to a known state for predictable system function.

Other blocks provided include PLLs, DLLs and configuration functions. The LatticeECP2/M architecture provides two General PLLs (GPLL) and up to six Standard PLLs (SPLL) per device. In addition, each LatticeECP2/M family member provides two DLLs per device. The GPLLs and DLLs blocks are located in pairs at the end of the bottom-most EBR row; the DLL block is located towards the edge of the device. The SPLL blocks are located at the end of the other EBR/DSP rows.

The configuration block that supports features such as configuration bit-stream decryption, transparent updates and dual boot support is located toward the center of this EBR row. The Ball Grid Array (BGA) package devices in the LatticeECP2/M family supports a sysCONFIG™ port located in the corner between banks four and five, which allows for serial or parallel device configuration.

In addition, every device in the family has a JTAG port. This family also provides an on-chip oscillator. The LatticeECP2/M devices use 1.2V as their core voltage.

Figure 2-4. Slice Diagram



For Slices 0 and 2, memory control signals are generated from Slice 1 as follows:

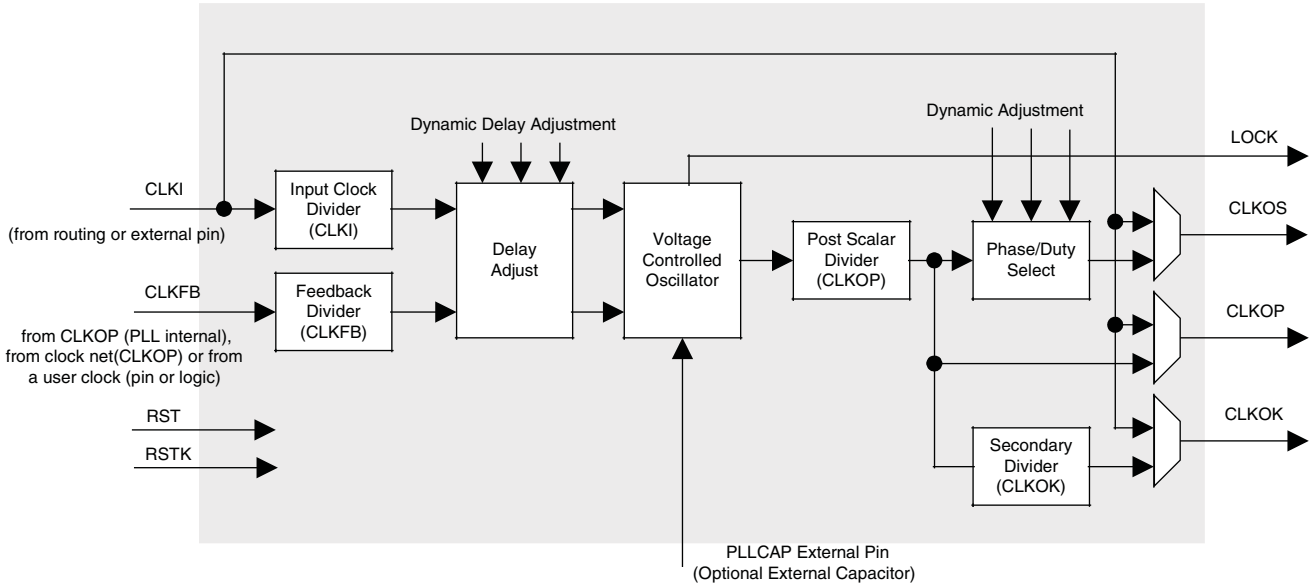
WCK is CLK
WRE is from LSR
DI[3:2] for Slice 2 and DI[1:0] for Slice 0 data
WAD [A:D] is a 4bit address from slice 1 LUT input

Table 2-2. Slice Signal Descriptions

Function	Type	Signal Names	Description
Input	Data signal	A0, B0, C0, D0	Inputs to LUT4
Input	Data signal	A1, B1, C1, D1	Inputs to LUT4
Input	Multi-purpose	M0	Multipurpose Input
Input	Multi-purpose	M1	Multipurpose Input
Input	Control signal	CE	Clock Enable
Input	Control signal	LSR	Local Set/Reset
Input	Control signal	CLK	System Clock
Input	Inter-PFU signal	FC	Fast Carry-in[1]
Input	Inter-slice signal	FXA	Intermediate signal to generate LUT6 and LUT7
Input	Inter-slice signal	FXB	Intermediate signal to generate LUT6 and LUT7
Output	Data signals	F0, F1	LUT4 output register bypass signals
Output	Data signals	Q0, Q1	Register outputs
Output	Data signals	OFX0	Output of a LUT5 MUX
Output	Data signals	OFX1	Output of a LUT6, LUT7, LUT8[2] MUX depending on the slice
Output	Inter-PFU signal	FCO	Slice 2 of each PFU is the fast carry chain output[1]

1. See Figure 2-4 for connection details.
2. Requires two PFUs.

Figure 2-5. General Purpose PLL (GPLL) Diagram



Standard PLL (SPLL)

Some of the larger devices have two to six Standard PLLs (SPLLs). SPLLs have the same features as GPLLs but without delay adjustment capability. SPLLs also provide different parametric specifications. For more information, please see the list of additional technical documentation at the end of this data sheet.

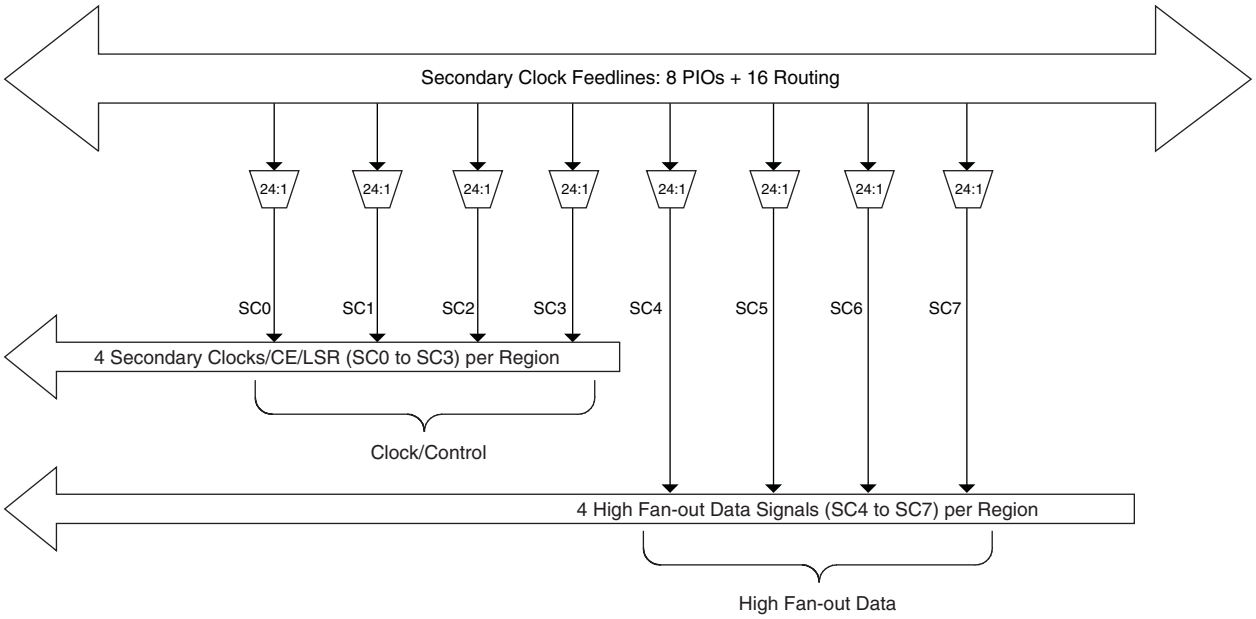
Table 2-4 provides a description of the signals in the GPLL and SPLL blocks.

Table 2-4. GPLL and SPLL Blocks Signal Descriptions

Signal	I/O	Description
CLKI	I	Clock input from external pin or routing
CLKFB	I	PLL feedback input from CLKOP (PLL internal), from clock net (CLKOP) or from a user clock (PIN or logic)
RST	I	“1” to reset PLL counters, VCO, charge pumps and M-dividers
RSTK	I	“1” to reset K-divider
CLKOS	O	PLL output clock to clock tree (phase shifted/duty cycle changed)
CLKOP	O	PLL output clock to clock tree (no phase shift)
CLKOK	O	PLL output to clock tree through secondary clock divider
LOCK	O	“1” indicates PLL LOCK to CLKI
DDAMODE[1]	I	Dynamic Delay Enable. “1”: Pin control (dynamic), “0”: Fuse Control (static)
DDAIZR[1]	I	Dynamic Delay Zero. “1”: delay = 0, “0”: delay = on
DDAILAG[1]	I	Dynamic Delay Lag/Lead. “1”: Lead, “0”: Lag
DDAIDEL[2:0][1]	I	Dynamic Delay Input
DPA MODES	I	DPA (Dynamic Phase Adjust/Duty Cycle Select) mode
DPHASE [3:0]	I	DPA Phase Adjust inputs
DDDUTY [3:0]	—	DPA Duty Cycle Select inputs

1. These signals are not available in SPLL.

Figure 2-16. Secondary Clock Selection



Slice Clock Selection

Figure 2-17 shows the clock selections and Figure 2-18 shows the control selections for Slice0 through Slice2. All the primary clocks and the four secondary clocks are routed to this clock selection mux. Other signals can be used as a clock input to the slices via routing. Slice controls are generated from the secondary clocks or other signals connected via routing.

If none of the signals are selected for both clock and control then the default value of the mux output is 1. Slice 3 does not have any registers; therefore it does not have the clock or control muxes.

Figure 2-17. Slice0 through Slice2 Clock Selection

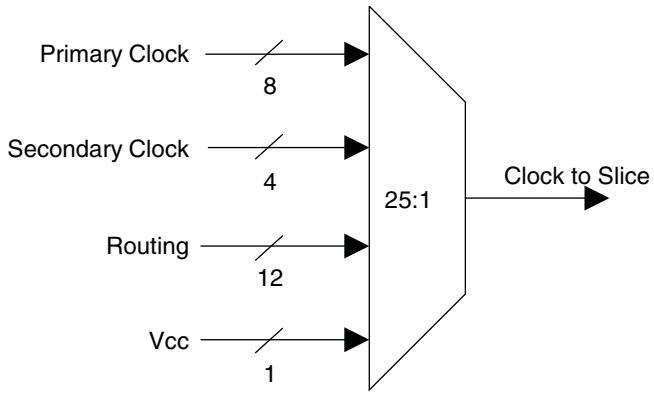
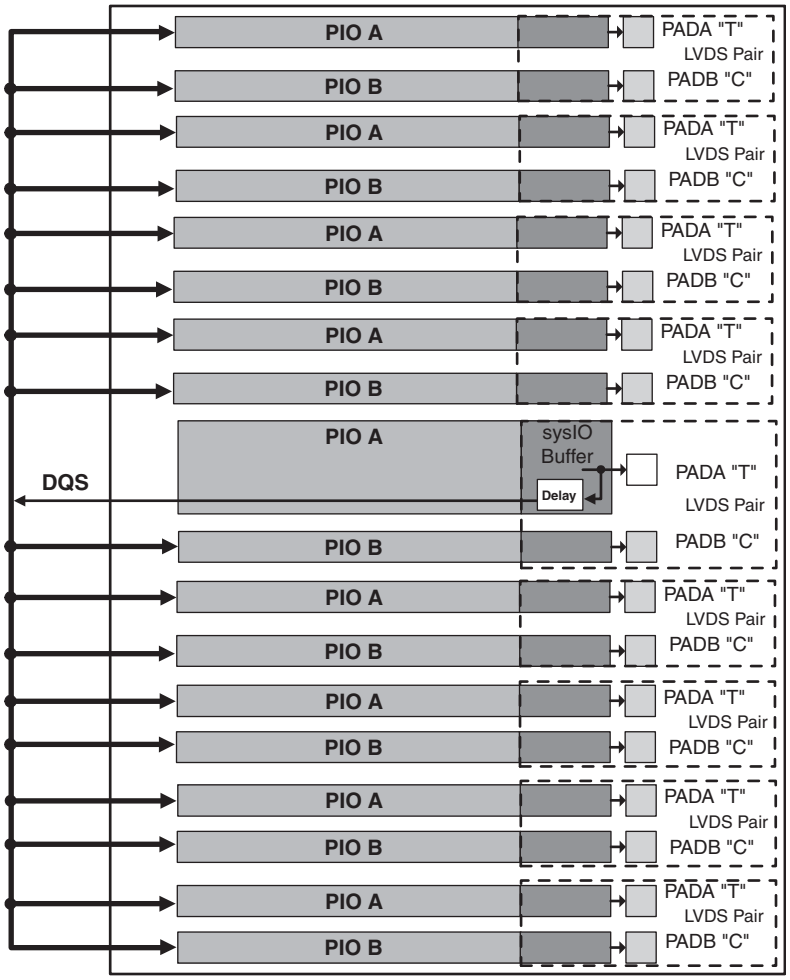


Figure 2-34. DQS Input Routing for the Bottom Edge of the Device



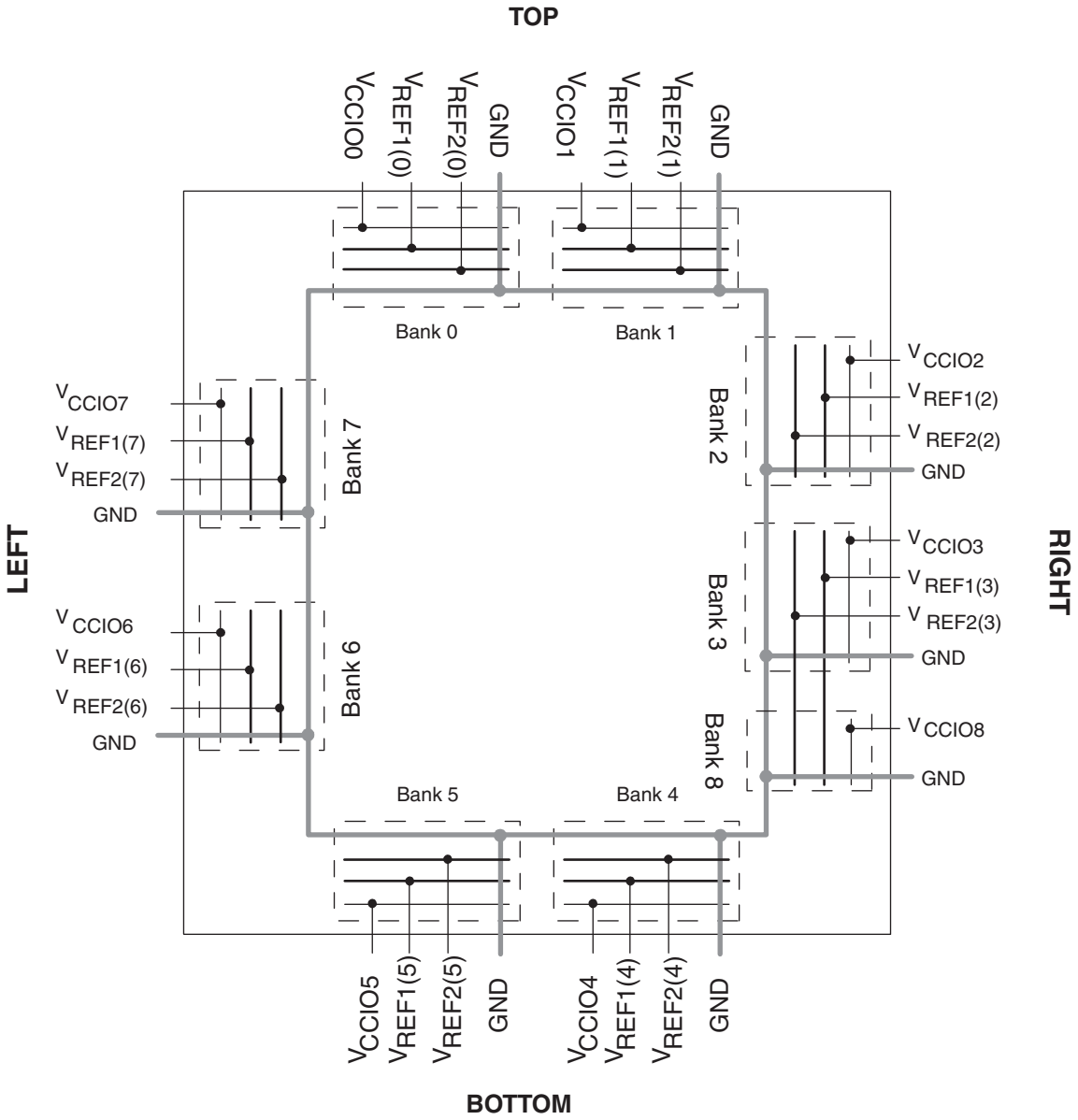
DLL Calibrated DQS Delay Block

Source synchronous interfaces generally require the input clock to be adjusted in order to correctly capture data at the input register. For most interfaces a PLL is used for this adjustment. However, in DDR memories the clock (referred to as DQS) is not free-running so this approach cannot be used. The DQS Delay block provides the required clock alignment for DDR memory interfaces.

The DQS signal (selected PIOs only, as shown in Figure 2-35) feeds from the PAD through a DQS delay element to a dedicated DQS routing resource. The DQS signal also feeds polarity control logic, which controls the polarity of the clock to the sync registers in the input register blocks. Figure 2-35 and Figure 2-36 show how the DQS transition signals are routed to the PIOs.

The temperature, voltage and process variations of the DQS delay block are compensated by a set of calibration (6-bit bus) signals from two dedicated DLLs (DDR_DLL) on opposite sides of the device. Each DLL compensates DQS delays in its half of the device as shown in Figure 2-35. The DLL loop is compensated for temperature, voltage and process variations by the system clock and feedback loop.

Figure 2-37. LatticeECP2 Banks



O standards (together with their supply and reference voltages) supported by LatticeECP2/M devices. For further information about utilizing the sysI/O buffer to support a variety of standards please see the the list of additional technical information at the end of this data sheet.

Table 2-13. Supported Input Standards

Input Standard	V_{REF} (Nom.)	V_{CCIO}[1] (Nom.)
Single Ended Interfaces		
LVTTL	—	—
LVCMOS33	—	—
LVCMOS25	—	—
LVCMOS18	—	1.8
LVCMOS15	—	1.5
LVCMOS12	—	—
PCI 33	—	3.3
HSTL18 Class I, II	0.9	—
HSTL15 Class I	0.75	—
SSTL3 Class I, II	1.5	—
SSTL2 Class I, II	1.25	—
SSTL18 Class I, II	0.9	—
Differential Interfaces		
Differential SSTL18 Class I, II	—	—
Differential SSTL2 Class I, II	—	—
Differential SSTL3 Class I, II	—	—
Differential HSTL15 Class I	—	—
Differential HSTL18 Class I, II	—	—
LVDS, MLVDS, LVPECL, BLVDS, RSDS	—	—

1 When not specified, V_{CCIO} can be set anywhere in the valid operating range (page 3-1).

LatticeECP2/M Family Data Sheet DC and Switching Characteristics

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Absolute Maximum Ratings[1, 2, 3]

Supply Voltage V_{CC} . . . . . -0.5 to 1.32V

Supply Voltage V_{CCAUX} . . . . . -0.5 to 3.75V

Supply Voltage V_{CCJ} . . . . . -0.5 to 3.75V

Output Supply Voltage V_{CCIO} . . . . . -0.5 to 3.75V

Input or I/O Tristate Voltage Applied[4]. . . . . -0.5 to 3.75V

Storage Temperature (Ambient) . . . . . -65 to 150°C

Junction Temperature (Tj) . . . . . +125°C

1. Stress above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice Thermal Management document is required.
3. All voltages referenced to GND.
4. Overshoot and undershoot of -2V to (V_{IHMAX} + 2) volts is permitted for a duration of <20ns.

Recommended Operating Conditions[7]

Symbol	Parameter	Min.	Max.	Units
V_{CC}[1, 4, 5]	Core Supply Voltage	1.14	1.26	V
V_{CCAUX}[1, 3, 4, 5]	Auxiliary Supply Voltage	3.135	3.465	V
V_{CCPLL}	PLL Supply Voltage	1.14	1.26	V
V_{CCIO}[1, 2, 4]	I/O Driver Supply Voltage	1.14	3.465	V
V_{CCJ}[1]	Supply Voltage for IEEE 1149.1 Test Access Port	1.14	3.465	V
t_{JCOM}	Junction Temperature, Commercial Operation	0	85	°C
t_{JIND}	Junction Temperature, Industrial Operation	-40	100	°C
SERDES External Power Supply (For LatticeECP2M Family Only)				
V_{CCIB}	Input Buffer Power Supply (1.2V)	1.14	1.26	V
	Input Buffer Power Supply (1.5V)	1.425	1.575	V
V_{CCOB}	Output Buffer Power Supply (1.2V)	1.14	1.26	V
	Output Buffer Power Supply (1.5V)	1.425	1.575	V
$V_{CCAUX33}$	Termination Resistor Switching Power Supply	3.135	3.465	V
V_{CCRX}[6]	Receive Power Supply	1.14	1.26	V
V_{CCTX}[6]	Transmit Power Supply	1.14	1.26	V

LatticeECP2M Supply Current (Standby)[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply Current	ECP2M20	25	mA
		ECP2M35	50	mA
		ECP2M50	85	mA
		ECP2M70	100	mA
		ECP2M100	100	mA
I_{CCAUX}	Auxiliary Power Supply Current	ECP2M20	24	mA
		ECP2M35	24	mA
		ECP2M50	24	mA
		ECP2M70	24	mA
		ECP2M100	24	mA
I_{CCGPLL}	GPLL Power Supply Current (per GPLL)	All Devices	0.5	mA
I_{CCSPLL}	GPLL Power Supply Current (per SPLL)	All Devices	0.5	mA
I_{CCIO}	Bank Power Supply Current (Per Bank)	ECP2M20	2	mA
		ECP2M35	2	mA
		ECP2M50	2	mA
		ECP2M70	2	mA
		ECP2M100	2	mA
I_{CCJ}	V_{CCJ} Power Supply Current	All Devices	3	mA

1. For further information about supply current, please see the list of additional technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
3. Frequency 0MHz.
4. Pattern represents a “blank” configuration data file.
5. T_J = 25°C, power supplies at normal voltage.

LatticeECP2 Power Supply and NC

Signals	144 TQFP[3]	208 PQFP[3]	256 fpBGA[4]	484 fpBGA[4]
VCC	16, 22, 29, 48, 54, 83, 94, 102, 128, 135	12, 19, 28, 40, 74, 80, 97, 116, 129, 140, 146, 171, 188, 198	**LFE2-6:** G7, G9, G10, H7, J10, K10, K8 **LFE2-12/LFE2-20:** G7, G9, G10, H7, J10, K10, K8	**LFE2-12/LFE2-20:** N6, N18, J10, J11, J12, J13, K14, K9, L14, L9, M14, M9, N14, N9, P10, P11, P12, P13 **LFE2-35/LFE2-50:** J10, J11, J12, J13, K14, K9, L14, L9, M14, M9, N14, N9, P10, P11, P12, P13
VCCIO0	139	195, 206	C5, E7	G10, G9, H8, H9
VCCIO1	117	162, 170	C12, E10	G11, G12, G13, G14
VCCIO2	106	143, 148	E14, G12	H14, H15, J15, K16
VCCIO3	89	123, 135	K12, M14	L16, M16, N16, P16
VCCIO4	64	93, 100	M10, P12	R14, T12, T13, T14
VCCIO5	42	55, 63	M7, P5	R9, T10, T11, T9
VCCIO6	31	38, 44	K5, M3	N7, P7, P8, R8
VCCIO7	9	10, 14	E3, G5	J8, K7, L7, M7
VCCIO8	85	113, 118	T15	P15, R15
VCCJ	35	51	K7	T8
VCCAUX	6, 39, 90, 142	7, 30, 70, 86, 125, 151, 174, 190	G8, H10, J7, K9	G5, K5, R5, V7, V11, V8, V13, V15, M17, P17, E17, G18, D11, F13, C5, E6
VCCPLL	None	None	None	**LFE2-12/LFE2-20:** None **LFE2-35:** N6, N18 **LFE2-50:** N6, N18, K6, J16
GND[1]	11, 21, 30, 47, 51, 61, 81, 95, 105, 120, 133, 138	5, 13, 17, 25, 32, 42, 60, 68, 77, 81, 89, 102, 115, 122, 139, 145, 159, 169, 175, 184, 192, 201	A1, A16, B12, B5, C8, E15, E2, H14, H8, H9, J3, J8, J9, M15, M2, P9, R12, R5, T1, T16	A22, AA19, AA4, AB1, AB22, B19, B4, C14, C9, D2, D21, F17, F6, H10, H11, H12, H13, J14, J20, J3, J9, K10, K11, K12, K13, K15, K8, L10, L11, L12, L13, L15, L8, M10, M11, M12, M13, M15, M8, N10, N11, N12, N13, N15, N8, P14, P20, P3, P9, R10, R11, R12, R13, U17, U6, W2, W21, Y14, Y9, A1
NC[2]	**LFE2-6:** 45, 46, 124, 127 **LFE2-12:** 127	None	**LFE2-6:** K6, R3, P4 **LFE2-12/LFE2-20:** None	**LFE2-12:** E3, F3, F1, H4, F2, H5, G1, G3, G2, G4, K6, N1, M2, N2, M1, N3, N5, N4, P5, N19, M19, J22, L22, H22, K22, J16, D22, F21, E21, E22, H19, G20, G19, F20, C21, C22, H6, J6, H3, H2, H17, H16, H20, H18 **LFE2-20/LFE2-35:** K6, J16, H6, J6, H3, H2, H17, H16, H20, H18 **LFE2-50:** None

1. All grounds must be electrically connected at the board level. For fpBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
2. NC pins should not be connected to any active signals, VCC or GND.
3. Pin orientation follows the conventional order from the pin 1 marking of the top side view and counter-clockwise.
4. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
C17	PT58B	1		C
A18	PT58A	1		T
VCCIO	VCCIO1	1		
H16	PT57B	1	PCLKC1_0	C
F16	PT57A	1	PCLKT1_0	T
K16	XRES	1		
E16	PT55B	0	PCLKC0_0	C
GND	GNDIO0	-		
G16	PT55A	0	PCLKT0_0	T
B17	PT54B	0		C
A17	PT54A	0		T
J15	PT53B	0		C
VCCIO	VCCIO0	0		
J16	PT53A	0		T
C16	PT52B	0		C
D16	PT52A	0		T
F15	PT51B	0		C
H15	PT51A	0		T
E15	PT50B	0		C
GND	GNDIO0	-		
G15	PT50A	0		T
C15	PT49B	0		C
VCCIO	VCCIO0	0		
D15	PT49A	0		T
B16	PT48B	0		C
A16	PT48A	0		T
E14	PT47B	0		C
G14	PT47A	0		T
B15	PT46B	0		C
A15	PT46A	0		T
GND	GNDIO0	-		
H14	PT45B	0		C
F14	PT45A	0		T
D14	PT44B	0		C
C14	PT44A	0		T
VCCIO	VCCIO0	0		
G13	PT43B	0		C
E13	PT43A	0		T
B14	PT42B	0		C
A14	PT42A	0		T
GND	GNDIO0	-		
H13	PT41B	0		C
F13	PT41A	0		T

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
C13	GND	-		
C18	GND	-		
C23	GND	-		
C28	GND	-		
C3	GND	-		
C8	GND	-		
H28	GND	-		
H3	GND	-		
L14	GND	-		
L15	GND	-		
L16	GND	-		
L17	GND	-		
M12	GND	-		
M13	GND	-		
M14	GND	-		
M15	GND	-		
M16	GND	-		
M17	GND	-		
M18	GND	-		
M19	GND	-		
N12	GND	-		
N13	GND	-		
N14	GND	-		
N15	GND	-		
N16	GND	-		
N17	GND	-		
N18	GND	-		
N19	GND	-		
N28	GND	-		
N3	GND	-		
P11	GND	-		
P12	GND	-		
P13	GND	-		
P14	GND	-		
P15	GND	-		
P16	GND	-		
P17	GND	-		
P18	GND	-		
P19	GND	-		
P20	GND	-		
R11	GND	-		
R12	GND	-		
R13	GND	-		

LFE2M50E/SE Logic Signal Connections: 484 fpBGA

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
D1	PL2A	7	LDQ6	T (LVDS)*
E1	PL2B	7	LDQ6	C (LVDS)*
F1	PL3A	7	LDQ6	T
F2	PL3B	7	LDQ6	C
F5	PL4A	7	LDQ6	T (LVDS)*
VCCIO	VCCIO7	7		
G6	PL4B	7	LDQ6	C (LVDS)*
F4	PL5A	7	LDQ6	T
F3	PL5B	7	LDQ6	C
G1	PL6A	7	LDQS6	T (LVDS)*
GNDIO	GNDIO7	-		
G2	PL6B	7	LDQ6	C (LVDS)*
H1	PL7A	7	LDQ6	T
H2	PL7B	7	LDQ6	C
VCCIO	VCCIO7	7		
H7	PL8A	7	LDQ6	T (LVDS)*
H6	PL8B	7	LDQ6	C (LVDS)*
G3	PL9A	7	VREF2_7/LDQ6	T
H3	PL9B	7	VREF1_7/LDQ6	C
GNDIO	GNDIO7	-		
VCCIO	VCCIO7	7		
H5	PL11A	7	LUM0_SPLLT_IN_A	T (LVDS)*
H4	PL11B	7	LUM0_SPLLC_IN_A	C (LVDS)*
J1	PL12A	7	LUM0_SPLLT_FB_A	T
J2	PL12B	7	LUM0_SPLLC_FB_A	C
GNDIO	GNDIO7	-		
J3	PL13A	7		T (LVDS)*
J4	PL13B	7		C (LVDS)*
J7	PL14A	7		T
VCCIO	VCCIO7	7		
J6	PL14B	7		C
GNDIO	GNDIO7	-		
VCCIO	VCCIO7	7		
K1	PL32A	7	LUM3_SPLLT_IN_A/LDQ36	T (LVDS)*
K2	PL32B	7	LUM3_SPLLC_IN_A/LDQ36	C (LVDS)*
J5	PL33A	7	LUM3_SPLLT_FB_A/LDQ36	T
K5	PL33B	7	LUM3_SPLLC_FB_A/LDQ36	C
VCCIO	VCCIO7	7		
K7	PL34A	7	LDQ36	T (LVDS)*
K6	PL34B	7	LDQ36	C (LVDS)*
L6	PL35A	7	LDQ36	T
L7	PL35B	7	LDQ36	C

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
L11	GND	-		
L12	GND	-		
L13	GND	-		
M10	GND	-		
M11	GND	-		
M12	GND	-		
M13	GND	-		
N10	GND	-		
N11	GND	-		
N12	GND	-		
N13	GND	-		
N15	GND	-		
N20	GND	-		
N3	GND	-		
N8	GND	-		
P14	GND	-		
P9	GND	-		
R10	GND	-		
R13	GND	-		
T19	GND	-		
T4	GND	-		
W16	GND	-		
W2	GND	-		
W21	GND	-		
W7	GND	-		
Y10	GND	-		
Y13	GND	-		
Y15	NC	-		
W15	NC	-		
AB20	NC	-		
AB21	NC	-		
AA21	NC	-		
AA20	NC	-		
AB19	NC	-		
AB18	NC	-		
Y22	NC	-		
Y21	NC	-		
Y17	NC	-		
Y18	NC	-		
Y16	NC	-		
W17	NC	-		
Y19	NC	-		
Y20	NC	-		

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
W19	NC	-		
W18	NC	-		
V17	NC	-		
V18	NC	-		
D15	NC	-		
G14	NC	-		
G15	NC	-		
D14	NC	-		
E15	NC	-		
E14	NC	-		
F15	NC	-		
F14	NC	-		
F13	NC	-		
G12	NC	-		
G13	NC	-		
H8	VCCPLL	-		
H15	VCCPLL	-		
R8	VCCPLL	-		
R15	VCCPLL	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.
***For density migration, board design must take into account that these sysCONFIG pins are dual function for the lower density devices (ECP2M20 and ECP2M35). They can be either sysCONFIG pins or general purpose I/Os. These pins are dedicated pins for the higher density devices (ECP2M50, ECP2M70 and ECP2M100).
****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AA14	PB42B	4	BDQ42	C	PB51B	4	BDQ51	C
VCCIO	VCCIO4	4			VCCIO4	4		
GNDIO	GNDIO4	-			GNDIO4	-		
W17	PB65A	4	BDQ69	T	PB56A	4	BDQ60	T
AA19	PB65B	4	BDQ69	C	PB56B	4	BDQ60	C
AC15	PB48A	4	BDQ51	T	PB57A	4	BDQ60	T
Y18	PB68B	4	BDQ69	C	PB57B	4	BDQ60	C
AB15	PB49A	4	BDQ51	T	PB58A	4	BDQ60	T
AC16	PB49B	4	BDQ51	C	PB58B	4	BDQ60	C
VCCIO	VCCIO4	4			VCCIO4	4		
AA17	PB60A	4	BDQS60****	T	PB59A	4	BDQ60	T
AB16	PB50B	4	BDQ51	C	PB59B	4	BDQ60	C
GNDIO	GNDIO4	-			GNDIO4	-		
AA15	PB51A	4	BDQS51****	T	PB60A	4	BDQS60	T
W16	PB59B	4	BDQ60	C	PB60B	4	BDQ60	C
Y15	PB52A	4	BDQ51	T	PB61A	4	BDQ60	T
AC17	PB52B	4	BDQ51	C	PB61B	4	BDQ60	C
AA18	PB61A	4	BDQ60	T	PB62A	4	BDQ60	T
Y17	PB61B	4	BDQ60	C	PB62B	4	BDQ60	C
-	-	-			VCCIO4	4		
GNDIO	GNDIO4	-			-	-		
W15	PB54A	4	BDQ51	T	PB63A	4	BDQ60	T
AB17	PB54B	4	BDQ51	C	PB63B	4	BDQ60	C
GNDIO	GNDIO4	-			GNDIO4	-		
VCCIO	VCCIO4	4			VCCIO4	4		
V17	PB73A	4	BDQ69	T	PB72A	4	BDQ69	T
AA20	PB73B	4	BDQ69	C	PB72B	4	BDQ69	C
GNDIO	GNDIO4	-			GNDIO4	-		
AD13	VCC	-			LRC_SQ_VCCRX3	13		
AF14	PB47A	4	BDQ51	T	LRC_SQ_HDINP3	13		T
AE13	NC	-			LRC_SQ_VCCIB3	13		
AE14	PB41A	4	VREF2_4/BDQ42	T	LRC_SQ_HDINN3	13		C
AD16	VCC	-			LRC_SQ_VCCTX3	13		
AF17	PB51B	4	BDQ51	C	LRC_SQ_HDOUTP3	13		T
AF16	NC	-			LRC_SQ_VCCOB3	13		
AE17	PB50A	4	BDQ51	T	LRC_SQ_HDOUTN3	13		C
AD17	VCC	-			LRC_SQ_VCCTX2	13		
AE18	PB53B	4	BDQ51	C	LRC_SQ_HDOUTN2	13		C
AD18	NC	-			LRC_SQ_VCCOB2	13		
AF18	PB53A	4	BDQ51	T	LRC_SQ_HDOUTP2	13		T
AD14	VCC	-			LRC_SQ_VCCRX2	13		
AE15	PB48B	4	BDQ51	C	LRC_SQ_HDINN2	13		C
AD15	NC	-			LRC_SQ_VCCIB2	13		
AF15	PB47B	4	BDQ51	C	LRC_SQ_HDINP2	13		T
AD19	VCC	-			LRC_SQ_VCCP	13		
AC19	PB57B	4	BDQ60	C	LRC_SQ_REFCLKP	13		T
AB19	PB59A	4	BDQ60	T	LRC_SQ_REFCLKN	13		C
AE19	VCCAUX	-			LRC_SQ_VCCAUX33	13		

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AH12	VCC	-			LLC_SQ_VCCRX1	14		
AK8	PB16A	5	BDQ15	T	LLC_SQ_HDOUTP1	14		T
AH8	NC	-			LLC_SQ_VCCOB1	14		
AJ8	PB16B	5	BDQ15	C	LLC_SQ_HDOUTN1	14		C
AH9	VCC	-			LLC_SQ_VCCTX1	14		
AJ9	PB17B	5	BDQ15	C	LLC_SQ_HDOUTN0	14		C
AK10	NC	-			LLC_SQ_VCCOB0	14		
AK9	PB17A	5	BDQ15	T	LLC_SQ_HDOUTP0	14		T
AH10	VCC	-			LLC_SQ_VCCTX0	14		
AJ12	PB19B	5	BDQ15	C	LLC_SQ_HDINN0	14		C
AJ13	NC	-			LLC_SQ_VCCIB0	14		
AK12	PB19A	5	BDQ15	T	LLC_SQ_HDINP0	14		T
AH13	VCC	-			LLC_SQ_VCCRX0	14		
AF10	PB3A	5	BDQ6	T	PB30A	5	BDQ33	T
AE8	PB3B	5	BDQ6	C	PB30B	5	BDQ33	C
AE11	PB4A	5	BDQ6	T	PB31A	5	BDQ33	T
VCCIO	VCCIO5	5			VCCIO5	5		
AD9	PB4B	5	BDQ6	C	PB31B	5	BDQ33	C
AE10	PB5A	5	BDQ6	T	PB32A	5	BDQ33	T
AD10	PB5B	5	BDQ6	C	PB32B	5	BDQ33	C
AE13	PB6A	5	BDQS6	T	PB33A	5	BDQS33	T
GNDIO	GNDIO5	-			GNDIO5	-		
AC12	PB6B	5	BDQ6	C	PB33B	5	BDQ33	C
AG2	PB7A	5	BDQ6	T	PB34A	5	BDQ33	T
AG3	PB7B	5	BDQ6	C	PB34B	5	BDQ33	C
AD13	PB8A	5	BDQ6	T	PB35A	5	BDQ33	T
VCCIO	VCCIO5	5			VCCIO5	5		
AC13	PB8B	5	BDQ6	C	PB35B	5	BDQ33	C
AE14	PB9A	5	BDQ6	T	PB36A	5	BDQ33	T
AC14	PB9B	5	BDQ6	C	PB36B	5	BDQ33	C
AF3	PB10A	5	BDQ6	T	PB37A	5	BDQ33	T
GNDIO	GNDIO5	-			GNDIO5	-		
AF4	PB10B	5	BDQ6	C	PB37B	5	BDQ33	C
VCCIO	VCCIO5	5			-	-		
AG4	PB20A	5	BDQ24	T	PB38A	5	BDQ42	T
AG5	PB20B	5	BDQ24	C	PB38B	5	BDQ42	C
GNDIO	GNDIO5	-			-	-		
VCCIO	VCCIO5	5			-	-		
AD11	PB24A	5	BDQS24****	T	PB39A	5	BDQ42	T
AF13	PB24B	5	BDQ24	C	PB39B	5	BDQ42	C
AF12	PB25A	5	BDQ24	T	PB40A	5	BDQ42	T
-	-	-			VCCIO5	5		
AD14	PB25B	5	BDQ24	C	PB40B	5	BDQ42	C
AG8	PB26A	5	BDQ24	T	PB41A	5	BDQ42	T
AF8	PB26B	5	BDQ24	C	PB41B	5	BDQ42	C
AE15	PB27A	5	BDQ24	T	PB42A	5	BDQS42****	T
-	-	-			GNDIO5	-		
VCCIO	VCCIO5	5			-	-		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
D19	PT93B	1		C
E18	PT93A	1		T
D18	PT92B	1		C
C17	PT92A	1		T
A17	PT91B	1		C
B17	PT91A	1		T
GNDIO	GNDIO1	-		
VCCIO	VCCIO1	1		
J18	PT75B	1		C
J19	PT75A	1		T
H17	PT74B	1		C
J17	PT74A	1		T
F18	PT73B	1		C
F17	PT73A	1		T
GNDIO	GNDIO1	-		
A16	PT72B	1		C
B16	PT72A	1		T
G17	PT71B	1		C
G16	PT71A	1		T
VCCIO	VCCIO1	1		
H16	PT70B	1		C
F16	PT70A	1		T
J16	PT69B	1		C
G15	PT69A	1		T
GNDIO	GNDIO1	-		
C16	PT68B	1		C
D16	PT68A	1		T
J15	PT67B	1		C
H15	PT67A	1		T
VCCIO	VCCIO1	1		
A15	PT66B	1	VREF2_1	C
B15	PT66A	1	VREF1_1	T
F15	PT65B	1	PCLKC1_0	C
E16	PT65A	1	PCLKT1_0	T
C15	PT64B	0	PCLKC0_0	C
GNDIO	GNDIO0	-		
D15	PT64A	0	PCLKT0_0	T
C14	PT63B	0	VREF2_0	C
E15	PT63A	0	VREF1_0	T
G14	PT62B	0		C
VCCIO	VCCIO0	0		
J14	PT62A	0		T
F14	PT61B	0		C

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AA8	PL65A	6	LDQ64	T	PL73A	6	LDQ72	T
VCCIO	VCCIO6	6			VCCIO6	6		
Y9	PL65B	6	LDQ64	C	PL73B	6	LDQ72	C
AA6	PL66A	6	LDQ64	T (LVDS)*	PL74A	6	LDQ72	T (LVDS)*
AA7	PL66B	6	LDQ64	C (LVDS)*	PL74B	6	LDQ72	C (LVDS)*
AA4	PL67A	6	LDQ64	T	PL75A	6	LDQ72	T
GNDIO	GNDIO6	-			GNDIO6	-		
AA3	PL67B	6	LDQ64	C	PL75B	6	LDQ72	C
AA9	PL69A	6	LDQ73	T (LVDS)*	PL77A	6	LDQ81	T (LVDS)*
AA10	PL69B	6	LDQ73	C (LVDS)*	PL77B	6	LDQ81	C (LVDS)*
AA5	PL70A	6	LDQ73	T	PL78A	6	LDQ81	T
AB6	PL70B	6	LDQ73	C	PL78B	6	LDQ81	C
AB1	PL71A	6	LDQ73	T (LVDS)*	PL79A	6	LDQ81	T (LVDS)*
VCCIO	VCCIO6	6			VCCIO6	6		
AB2	PL71B	6	LDQ73	C (LVDS)*	PL79B	6	LDQ81	C (LVDS)*
AC8	PL72A	6	LDQ73	T	PL80A	6	LDQ81	T
AB10	PL72B	6	LDQ73	C	PL80B	6	LDQ81	C
AC1	PL73A	6	LDQS73	T (LVDS)*	PL81A	6	LDQS81	T (LVDS)*
GNDIO	GNDIO6	-			GNDIO6	-		
AC2	PL73B	6	LDQ73	C (LVDS)*	PL81B	6	LDQ81	C (LVDS)*
AB7	PL74A	6	LDQ73	T	PL82A	6	LDQ81	T
AB5	PL74B	6	LDQ73	C	PL82B	6	LDQ81	C
VCCIO	VCCIO6	6			VCCIO6	6		
AC3	PL75A	6	LDQ73	T (LVDS)*	PL83A	6	LDQ81	T (LVDS)*
AC4	PL75B	6	LDQ73	C (LVDS)*	PL83B	6	LDQ81	C (LVDS)*
AC10	PL76A	6	LDQ73	T	PL84A	6	LDQ81	T
AC9	PL76B	6	LDQ73	C	PL84B	6	LDQ81	C
GNDIO	GNDIO6	-			GNDIO6	-		
AC7	NC	-			PL86A	6	LDQ90	T (LVDS)*
AC5	NC	-			PL86B	6	LDQ90	C (LVDS)*
AC6	NC	-			PL87A	6	LDQ90	T
AD5	NC	-			PL87B	6	LDQ90	C
-	-	-			VCCIO6	6		
AD4	NC	-			PL88A	6	LDQ90	T (LVDS)*
AD3	NC	-			PL88B	6	LDQ90	C (LVDS)*
AD10	NC	-			PL89A	6	LDQ90	T
AD8	NC	-			PL89B	6	LDQ90	C
-	-	-			GNDIO6	-		
AD2	NC	-			PL90A	6	LDQS90	T (LVDS)*
AD1	NC	-			PL90B	6	LDQ90	C (LVDS)*
AD9	NC	-			PL91A	6	LDQ90	T
-	-	-			VCCIO6	6		
AC11	NC	-			PL91B	6	LDQ90	C
AD6	NC	-			PL92A	6	LDQ90	T (LVDS)*
AD7	NC	-			PL92B	6	LDQ90	C (LVDS)*
AE1	NC	-			PL93A	6	LDQ90	T
-	-	-			GNDIO6	-		
AE2	NC	-			PL93B	6	LDQ90	C
AF2	PL78A	6	LDQ82	T (LVDS)*	PL95A	6	LDQ99	T (LVDS)*

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M20SE-5FN484I	304	1.2V	-5	Lead-Free fpBGA	484	Ind	20
LFE2M20SE-6FN484I	304	1.2V	-6	Lead-Free fpBGA	484	Ind	20
LFE2M20SE-5FN256I	140	1.2V	-5	Lead-Free fpBGA	256	Ind	20
LFE2M20SE-6FN256I	140	1.2V	-6	Lead-Free fpBGA	256	Ind	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M35SE-5FN672I	410	1.2V	-5	Lead-Free fpBGA	672	Ind	35
LFE2M35SE-6FN672I	410	1.2V	-6	Lead-Free fpBGA	672	Ind	35
LFE2M35SE-5FN484I	303	1.2V	-5	Lead-Free fpBGA	484	Ind	35
LFE2M35SE-6FN484I	303	1.2V	-6	Lead-Free fpBGA	484	Ind	35
LFE2M35SE-5FN256I	140	1.2V	-5	Lead-Free fpBGA	256	Ind	35
LFE2M35SE-6FN256I	140	1.2V	-6	Lead-Free fpBGA	256	Ind	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M50SE-5FN900I	410	1.2V	-5	Lead-Free fpBGA	900	Ind	50
LFE2M50SE-6FN900I	410	1.2V	-6	Lead-Free fpBGA	900	Ind	50
LFE2M50SE-5FN672I	372	1.2V	-5	Lead-Free fpBGA	672	Ind	50
LFE2M50SE-6FN672I	372	1.2V	-6	Lead-Free fpBGA	672	Ind	50
LFE2M50SE-5FN484I	270	1.2V	-5	Lead-Free fpBGA	484	Ind	50
LFE2M50SE-6FN484I	270	1.2V	-6	Lead-Free fpBGA	484	Ind	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M70SE-5FN1152I	436	1.2V	-5	Lead-Free fpBGA	1152	Ind	70
LFE2M70SE-6FN1152I	436	1.2V	-6	Lead-Free fpBGA	1152	Ind	70
LFE2M70SE-5FN900I	416	1.2V	-5	Lead-Free fpBGA	900	Ind	70
LFE2M70SE-6FN900I	416	1.2V	-6	Lead-Free fpBGA	900	Ind	70

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M100SE-5FN1152I	520	1.2V	-5	Lead-Free fpBGA	1152	Ind	100
LFE2M100SE-6FN1152I	520	1.2V	-6	Lead-Free fpBGA	1152	Ind	100
LFE2M100SE-5FN900I	416	1.2V	-5	Lead-Free fpBGA	900	Ind	100
LFE2M100SE-6FN900I	416	1.2V	-6	Lead-Free fpBGA	900	Ind	100